

L Number	Hits	Search Text	DB	Time stamp
1	26	(water with ozone with tank)with(bubbl\$3 sparg\$3 mix\$3) and (ambient "room temperature" temperature)	JPO; DERWENT	2004/06/16 15:08
2	60	((water with ozone same(bubbl\$3 sparg\$3 mix\$3)) same (wafer semiconductor substrate))) and (temperature C celsius ambient)	JPO; DERWENT	2004/06/16 15:06
3	57	((((water with ozone same(bubbl\$3 sparg\$3 mix\$3)) same (wafer semiconductor substrate))) and (temperature C celsius ambient)) not ((water with ozone with tank)with(bubbl\$3 sparg\$3 mix\$3) and (ambient "room temperature" temperature))	JPO; DERWENT	2004/06/16 15:05
4	15	((water with ozone same(bubbl\$3 sparg\$3 mix\$3)) same (wafer semiconductor substrate))) and (temperature "&deg;" celsius ambient)	JPO; DERWENT	2004/06/16 15:06
5	0	6649018.pn. and (deg temperature)	JPO; DERWENT	2004/06/16 15:09
6	1	6649018.pn. and (deg temperature)	USPAT	2004/06/16 15:09
7	3	("5464480"   "6080531"   "6187216").PN.	USPAT	2004/06/16 15:09
8	3	("5464480"   "6080531"   "6187216").PN.) and (deg temperature)	USPAT	2004/06/16 15:10
-	422	134/159	USPAT	2004/01/30 10:43
-	1	6340643.pn.	USPAT	2003/08/07 12:36
-	4	("5405443"   "5599394"   "6059880"   "6245148").PN.	USPAT	2003/08/07 12:37
-	2	("5759918" "5695392").pn.	USPAT	2003/08/14 08:26
-	0	"0776730"	EPO	2003/08/14 08:26
-	0	0776730.ipc.	EPO	2003/08/14 08:27
-	0	776730.ipc.	EPO	2003/08/14 08:27
-	0	00776730.ipc.	EPO	2003/08/14 08:27
-	0	0776730.ipc.	EPO	2003/08/14 08:28
-	1171	Kubo	EPO	2003/08/14 08:28
-	11	Kubo and retaining	EPO	2003/08/14 08:28
-	2	5957764.pn. 5985039.pn. 0793261.ipc.	USPAT; EPO	2003/08/14 11:41
-	3	5957764.pn. 5985039.pn. "0793261"	USPAT; EPO	2003/08/14 11:42
-	1	"0793261"	USPAT; EPO	2003/08/14 11:43
-	0	ep.0793261.	USPAT; EPO	2003/08/14 11:44
-	1	"00793261"	USPAT; EPO	2003/08/14 11:44
-	0	"00793261"	EPO;	2003/08/14 11:45
-	236	156/345.11 156/345.23	DERWENT	
-	2807	134/1.3 134/119 134/120 134/136 134/137 134/138 134/140 134/157	USPAT	2003/08/14 13:53
-	1336	(134/1.3 134/119 134/120 134/136 134/137 134/138 134/140 134/157) and (wafer semiconductor substrate)	USPAT	2003/08/14 13:54
-	877	((134/1.3 134/119 134/120 134/136 134/137 134/138 134/140 134/157) and (wafer semiconductor substrate)) and (flip\$4 turn\$4 rotat\$6)	USPAT	2003/08/14 13:55
-	916	((134/1.3 134/119 134/120 134/136 134/137 134/138 134/140 134/157) and (wafer semiconductor substrate)) and etch\$3	USPAT	2003/08/14 13:56
-	423	134/159	USPAT	2003/08/14 13:57
-	162	156/345.11	USPAT;	2004/01/30 10:43
-	3	6383724.pn. 5464480.pn. 6187216.pn.	US-PGPUB	2004/02/02 14:32
-	2017	156/345.11 156/345.18 438/689 216/83 216/93	USPAT	2004/02/04 11:02
-	50	(156/345.11 156/345.18 438/689 216/83 216/93) and (water same ozone)	USPAT	2004/02/04 11:03
-	1	6649018.pn.	USPAT	2004/02/04 11:05
-	8	134/113	EPO;	2004/04/22 10:47
-			DERWENT	
-			EPO;	2004/04/22 10:47
-			DERWENT	
-	815	134/113	USPAT	2004/04/22 10:48
-	421	water same ozone same (sparger bubbl\$3)	EPO;	2004/06/03 15:23
-			DERWENT	

-	1369	water same ozone same (sparger bubbl\$3)	USPAT; US-PGPUB	2004/06/03 15:24
-	647	water with ozone with (sparger bubbl\$3)	USPAT; US-PGPUB	2004/06/03 15:25
-	26	"5750440"	USPAT	2004/06/04 14:25
-	3472	water and ozone and tank	EPO; JPO; DERWENT	2004/06/16 12:41
-	3407	water and ozone and tank	JPO; DERWENT	2004/06/16 12:41
-	2825	water same ozone same tank	JPO; DERWENT	2004/06/16 12:41
-	2216	water with ozone with tank	JPO; DERWENT	2004/06/16 12:42
-	738	(water with ozone with tank) and (bubbl\$3 sparg\$3 mix\$3)	JPO; DERWENT	2004/06/16 12:42
-	651	water with ozone with tank) same (bubbl\$3 sparg\$3 mix\$3	JPO; DERWENT	2004/06/16 12:52
-	539	water with ozone with tank) with (bubbl\$3 sparg\$3 mix\$3	JPO; DERWENT	2004/06/16 14:57
-	22	(water with ozone with tank) with (bubbl\$3 sparg\$3 mix\$3) and (wafer semiconductor substrate)	JPO; DERWENT	2004/06/16 12:45
-	2391	water with ozone same (bubbl\$3 sparg\$3 mix\$3)	JPO; DERWENT	2004/06/16 12:52
-	99	(water with ozone same (bubbl\$3 sparg\$3 mix\$3)) same (wafer semiconductor substrate)	JPO; DERWENT	2004/06/16 15:04
-	84	((water with ozone same (bubbl\$3 sparg\$3 mix\$3)) same (wafer semiconductor substrate)) not ((water with ozone with tank) with (bubbl\$3 sparg\$3 mix\$3) and (wafer semiconductor substrate))	JPO; DERWENT	2004/06/16 13:58